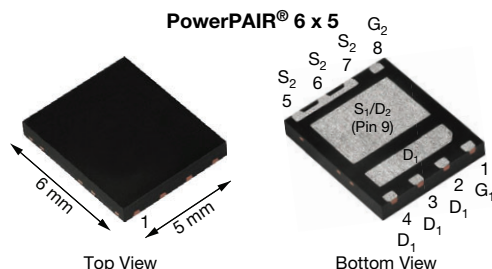


Dual N-Channel 30 V (D-S) MOSFET



FEATURES

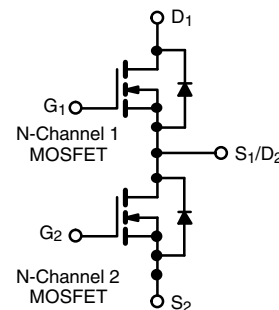
- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Notebook system power
- POL
- Synchronous buck converter



PRODUCT SUMMARY		
	CHANNEL-1	CHANNEL-2
V _{DS} (V)	30	30
R _{DS(on)} max. (Ω) at V _{GS} = 10 V	0.0120	0.0064
R _{DS(on)} max. (Ω) at V _{GS} = 4.5 V	0.0145	0.0083
Q _g typ. (nC)	6.8	21
I _D (A) ^a	16	16
Configuration	Dual	

ORDERING INFORMATION		
Package	PowerPAIR 6 x 5	
Lead (Pb)-free and halogen-free	SiZ902DT-T1-GE3	

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	CHANNEL-1	CHANNEL-2	UNIT
Drain-source voltage		V _{DS}	30	30	V
Gate-source voltage		V _{GS}	± 20	± 20	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C	I _D	16 ^a	16 ^a	A
	T _C = 70 °C		16 ^a	16 ^a	
	T _A = 25 °C		14.3 ^{b, c}	16 ^{a, b, c}	
	T _A = 70 °C		11.4 ^{b, c}	16 ^{a, b, c}	
Pulsed drain current (t = 300 μs)		I _{DM}	50	80	
Continuous source-drain diode current	T _C = 25 °C	I _S	16 ^a	16 ^a	
	T _A = 25 °C		3.4 ^{b, c}	4.1 ^{b, c}	
Single pulse avalanche current	L = 0.1 mH	I _{AS}	18	30	mJ
Single pulse avalanche energy		E _{AS}	16	45	
Maximum power dissipation	T _C = 25 °C	P _D	29	66	W
	T _C = 70 °C		18	42	
	T _A = 25 °C		4.2 ^{b, c}	5 ^{b, c}	
	T _A = 70 °C		2.7 ^{b, c}	3.2 ^{b, c}	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150		°C
Soldering recommendations (peak temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	CHANNEL-1		CHANNEL-2		UNIT
		TYP.	MAX.	TYP.	MAX.	
Maximum junction-to-ambient ^{b, f}	t ≤ 10 s	R _{thJA}	24	30	20	25
Maximum junction-to-case (drain)	Steady state	R _{thJC}	3.4	4.3	1.5	1.9

Notes

- Package limited
- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile (www.vishay.com/doc?73257). The PowerPAIR is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 65 °C/W for channel-1 and 57 °C/W for channel-2



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	Ch-1	30	-	-	V
			Ch-2	30	-	-	
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = 250 μA	Ch-1	-	33	-	mV/°C
			Ch-2	-	33	-	
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		Ch-1	-	-5	-	
			Ch-2	-	-4.6	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	Ch-1	1	-	2.2	V
			Ch-2	1	-	2.2	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +20 V	Ch-1	-	-	± 100	nA
			Ch-2	-	-	± 100	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	Ch-1	-	-	1	μA
			Ch-2	-	-	1	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	Ch-1	-	-	5	
			Ch-2	-	-	5	
On-state drain current ^b	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-1	20	-	-	A
			Ch-2	20	-	-	
Drain-source on-state resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 13.8 A	Ch-1	-	0.0100	0.0120	Ω
		V _{GS} = 10 V, I _D = 20 A	Ch-2	-	0.0053	0.0064	
		V _{GS} = 4.5 V, I _D = 12.6 A	Ch-1	-	0.0120	0.0145	
		V _{GS} = 4.5 V, I _D = 20 A	Ch-2	-	0.0068	0.0083	
Forward transconductance ^b	g _{fs}	V _{DS} = 10 V, I _D = 13.8 A	Ch-1	-	47	-	S
		V _{DS} = 10 V, I _D = 20 A	Ch-2	-	63	-	
Dynamic ^a							
Input capacitance	C _{iss}	Channel-1 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1	-	790	-	pF
			Ch-2	-	2600	-	
Output capacitance	C _{oss}		Ch-1	-	190	-	
			Ch-2	-	485	-	
Reverse transfer capacitance	C _{rss}	Channel-2 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1	-	76	-	nC
			Ch-2	-	215	-	
Total gate charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 13.8 A	Ch-1	-	14	21	
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A	Ch-2	-	43	65	
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 13.8 A	Ch-1	-	6.8	11	
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A	Ch-2	-	21	32	
Gate-source charge	Q _{gs}	Channel-1 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 13.8 A	Ch-1	-	2.6	-	nC
			Ch-2	-	8.1	-	
Gate-drain charge	Q _{gd}	Channel-2 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A	Ch-1	-	1.9	-	
			Ch-2	-	6.5	-	
Gate resistance	R _g	f = 1 MHz	Ch-1	0.4	2	-	Ω
			Ch-2	0.3	1.5	-	



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Dynamic ^a							
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 1.5 Ω, I _D ≡ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	15	30	ns
Rise time	t _r		Ch-2	-	23	50	
			Ch-1	-	12	20	
Turn-off delay time	t _{d(off)}		Ch-2	-	20	40	
		Ch-1	-	20	40		
Fall time	t _f	Ch-2	-	35	70		
		Ch-1	-	10	20		
Turn-on delay time	t _{d(on)}	Ch-2	-	10	20		
		Channel-1 V _{DD} = 15 V, R _L = 1.5 Ω, I _D ≡ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	10	20	
Rise time	t _r	Ch-2	-	22	25		
		Ch-1	-	12	20		
Turn-off delay time	t _{d(off)}	Ch-2	-	10	20		
		Channel-2 V _{DD} = 15 V, R _L = 1.5 Ω, I _D ≡ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	20	40	
Fall time	t _f	Ch-2	-	35	70		
		Ch-1	-	10	20		
		Ch-2	-	10	20		
		Drain-Source Body Diode Characteristics					
Continuous source-drain diode current	I _S	T _C = 25 °C	Ch-1	-	-	16	A
Pulse diode forward current ^a	I _{SM}		Ch-2	-	-	16	
		Ch-1	-	-	50		
		Ch-2	-	-	80		
Body diode voltage	V _{SD}	I _S = 10 A, V _{GS} = 0 V	Ch-1	-	0.85	1.2	V
Body diode reverse recovery time	t _{rr}		Ch-2	-	0.8	1.2	
		Channel-1 I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	20	40	ns
Ch-2	-		25	50			
Body diode reverse recovery charge	Q _{rr}		Ch-1	-	10	20	nC
			Ch-2	-	13	25	
Reverse recovery fall time	t _a	Channel-2 I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	11	-	ns
Reverse recovery rise time	t _b		Ch-2	-	12	-	
			Ch-1	-	9	-	
			Ch-2	-	13	-	

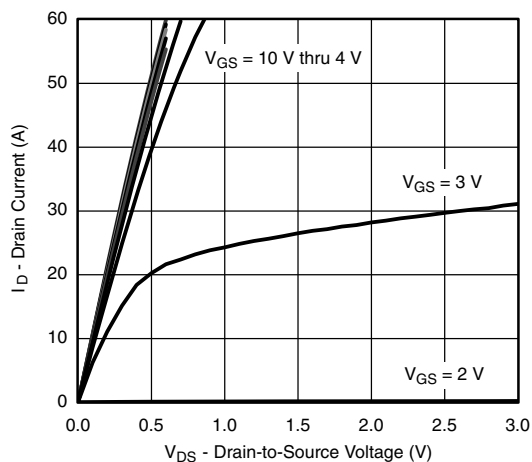
Notes

- a. Guaranteed by design, not subject to production testing
b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

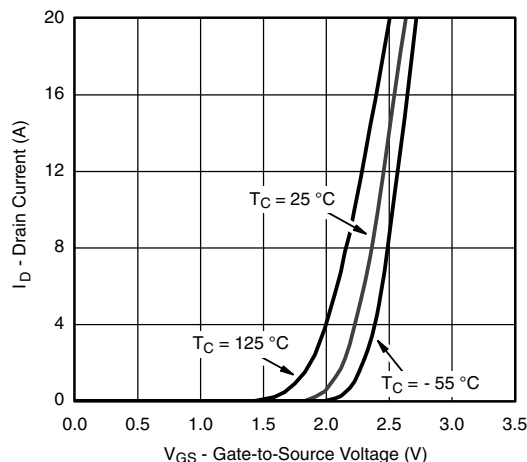
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



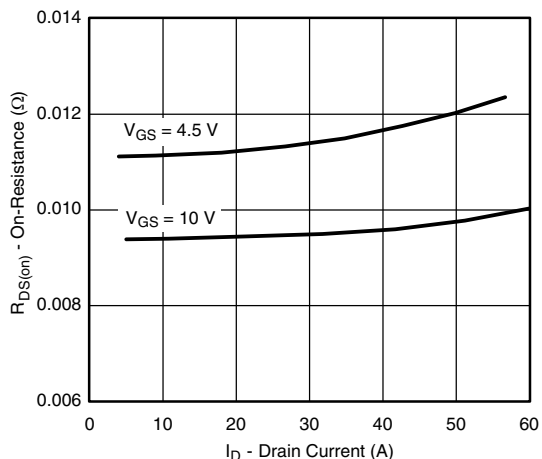
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



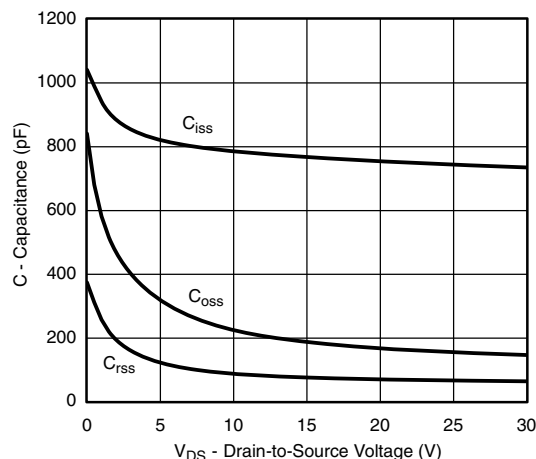
Output Characteristics



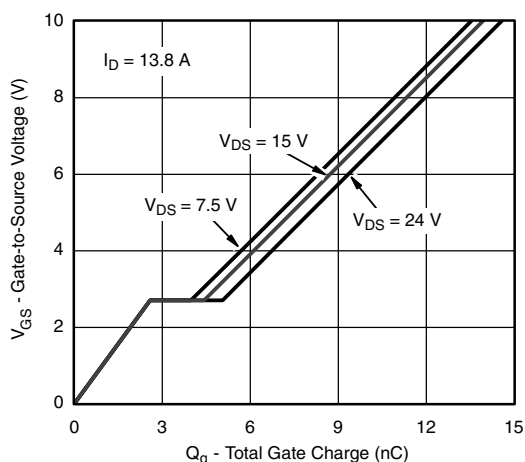
Transfer Characteristics



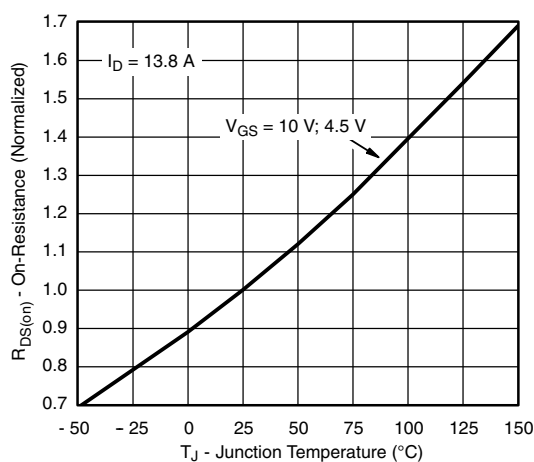
On-Resistance vs. Drain Current



Capacitance



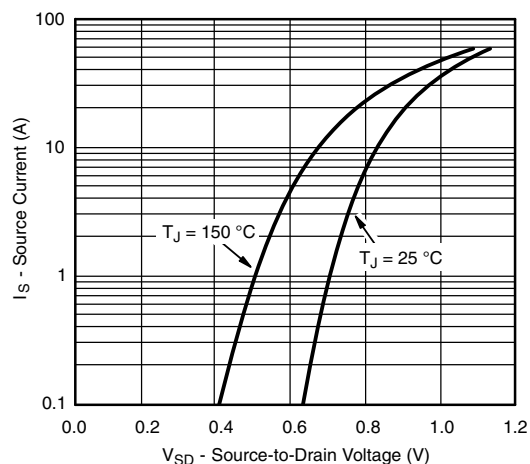
Gate Charge



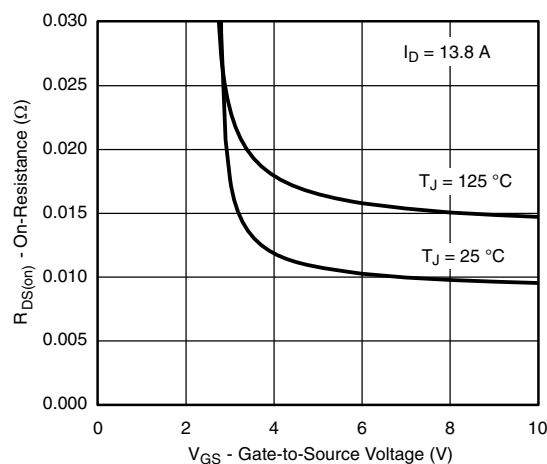
On-Resistance vs. Junction Temperature



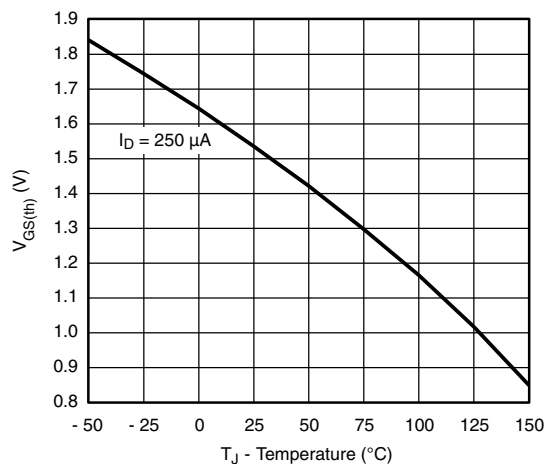
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



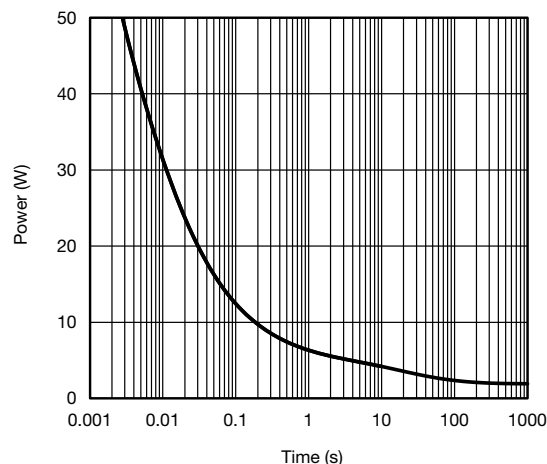
Source-Drain Diode Forward Voltage



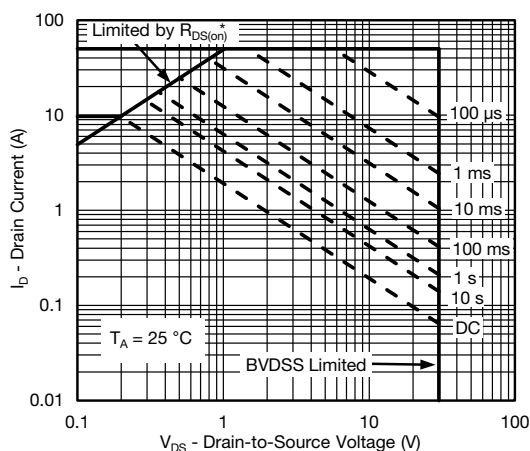
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



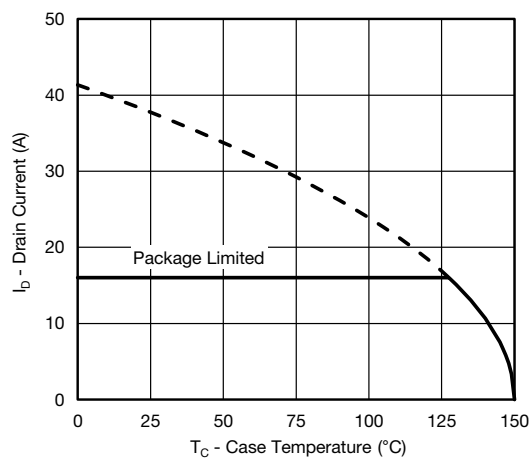
Single Pulse Power



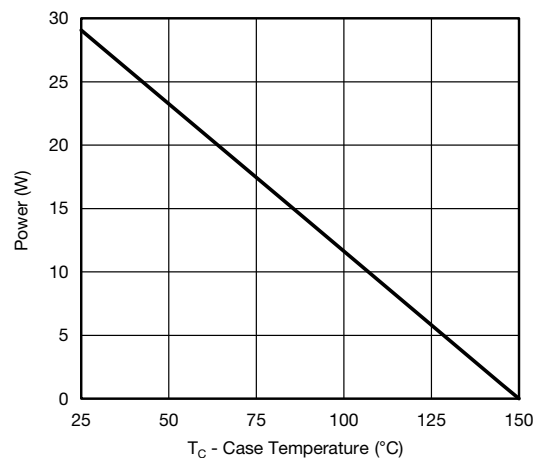
Safe Operating Area, Junction-to-Ambient



CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



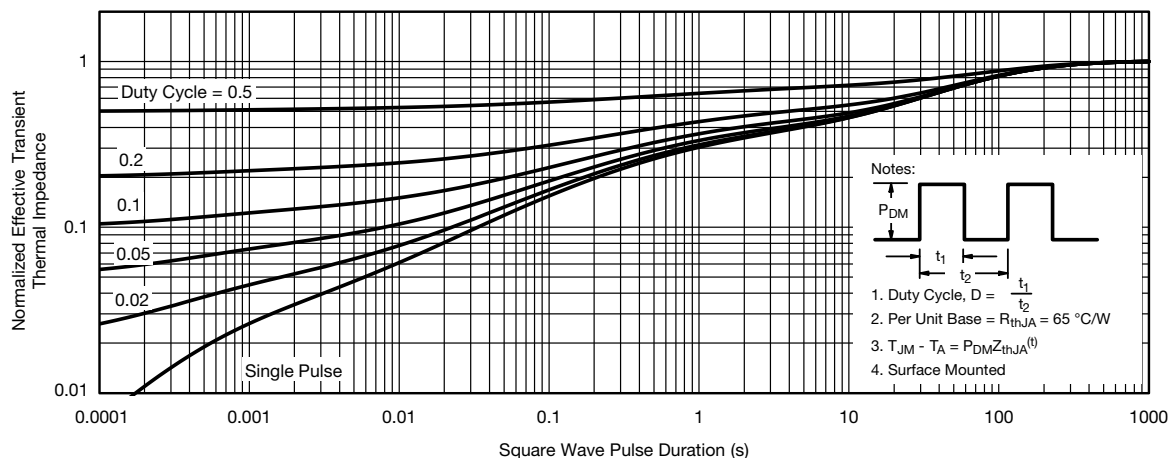
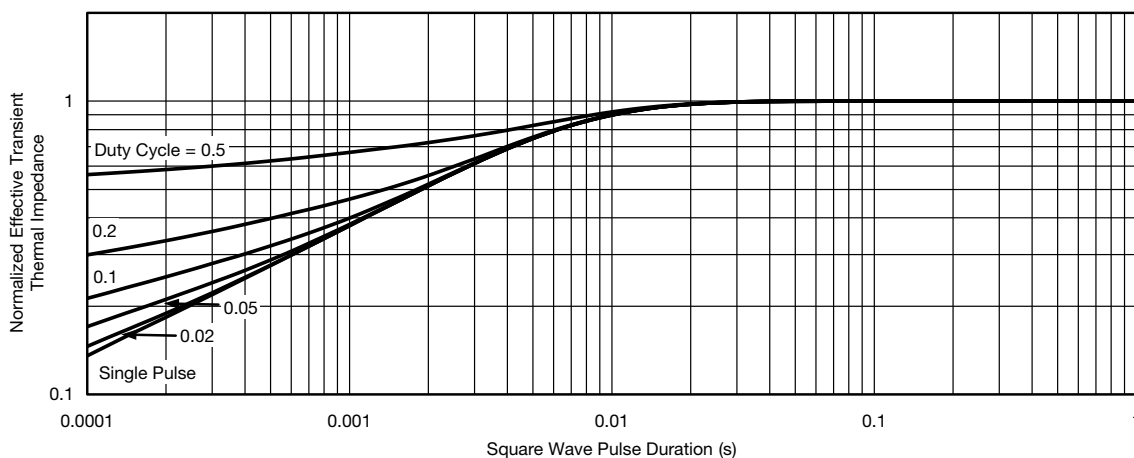
Current Derating ^a



Power, Junction-to-Case

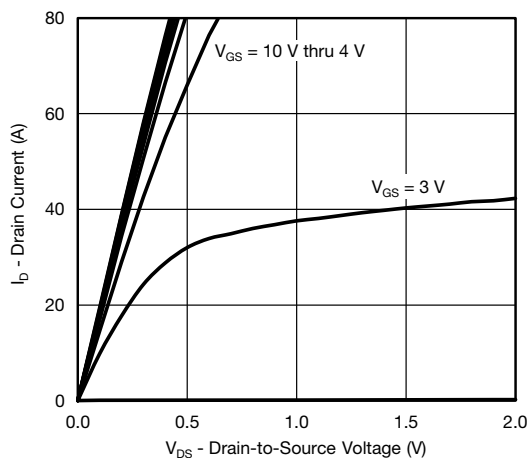
Note

- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

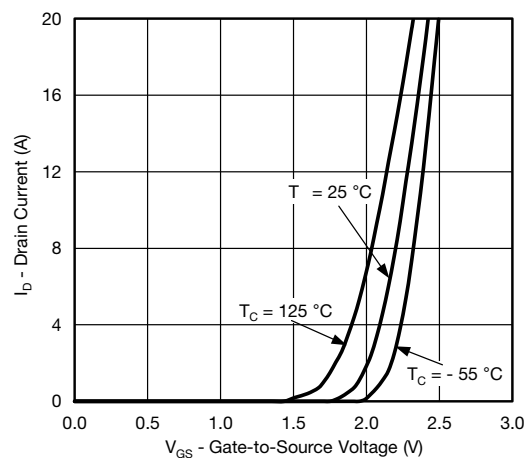
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Thermal Transient Impedance, Junction-to-Case



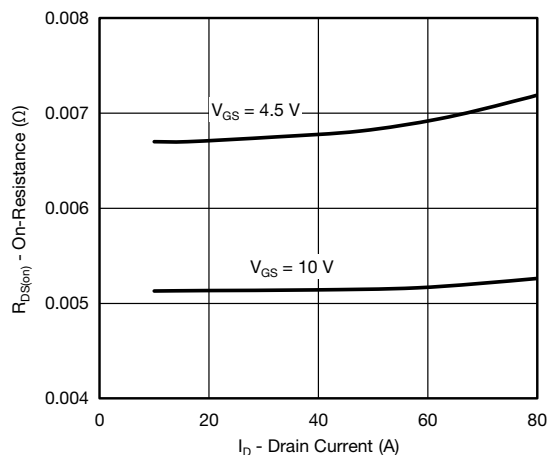
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



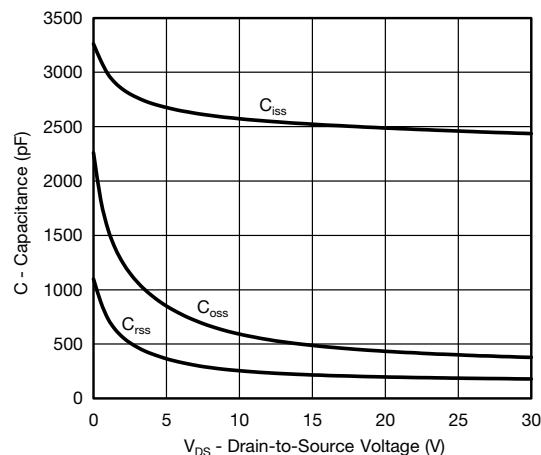
Output Characteristics



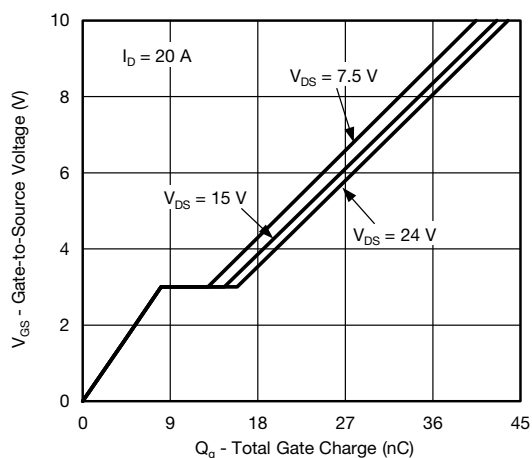
Transfer Characteristics



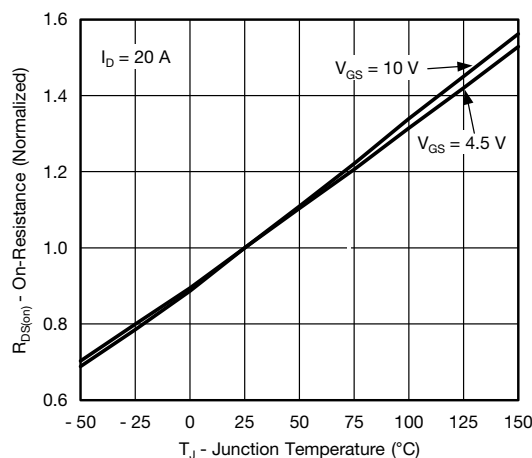
On-Resistance vs. Drain Current



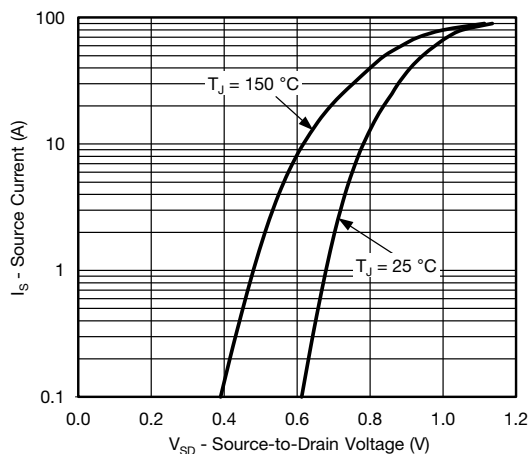
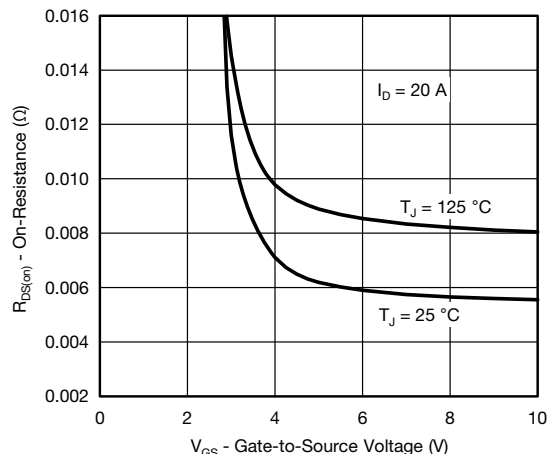
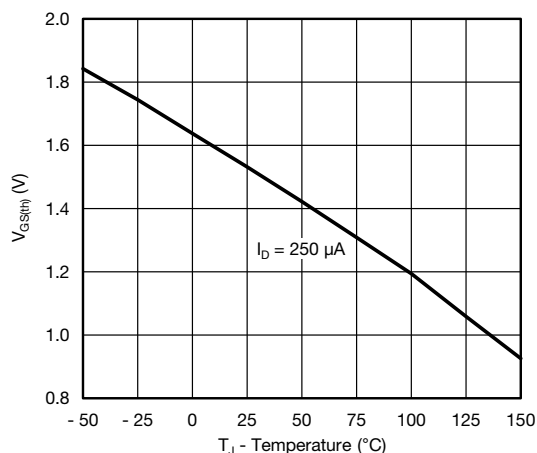
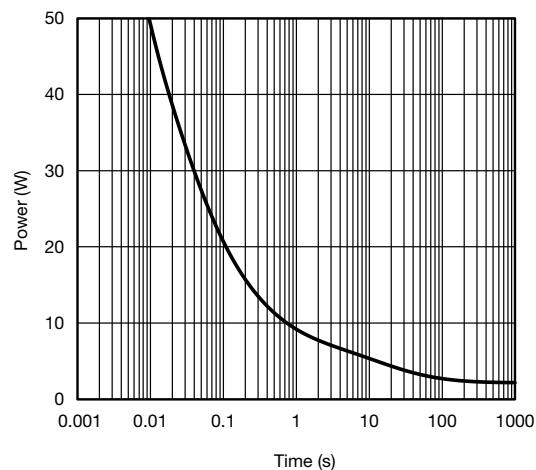
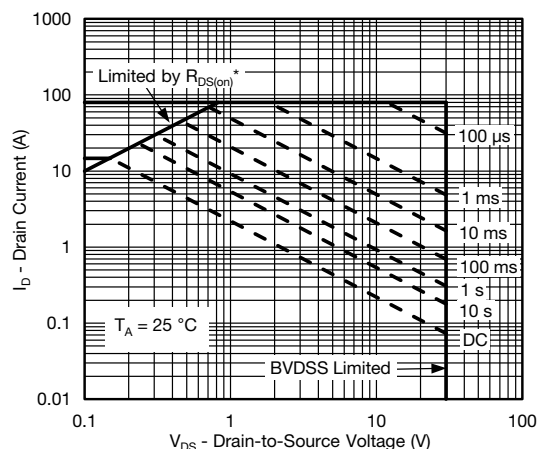
Capacitance

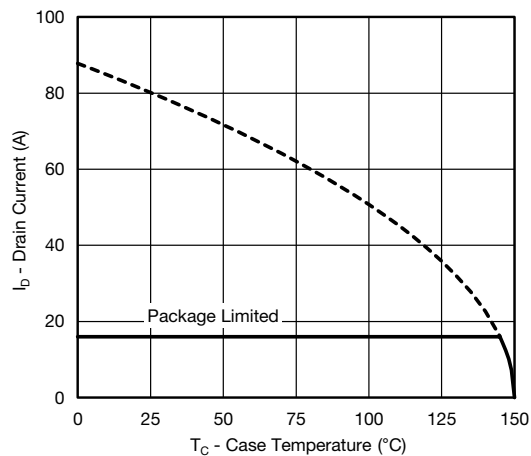
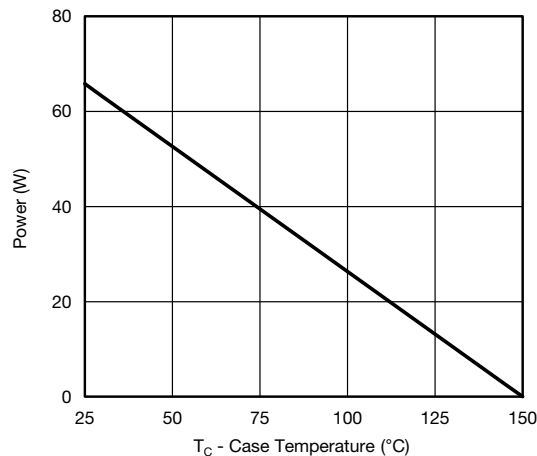


Gate Charge



On-Resistance vs. Junction Temperature

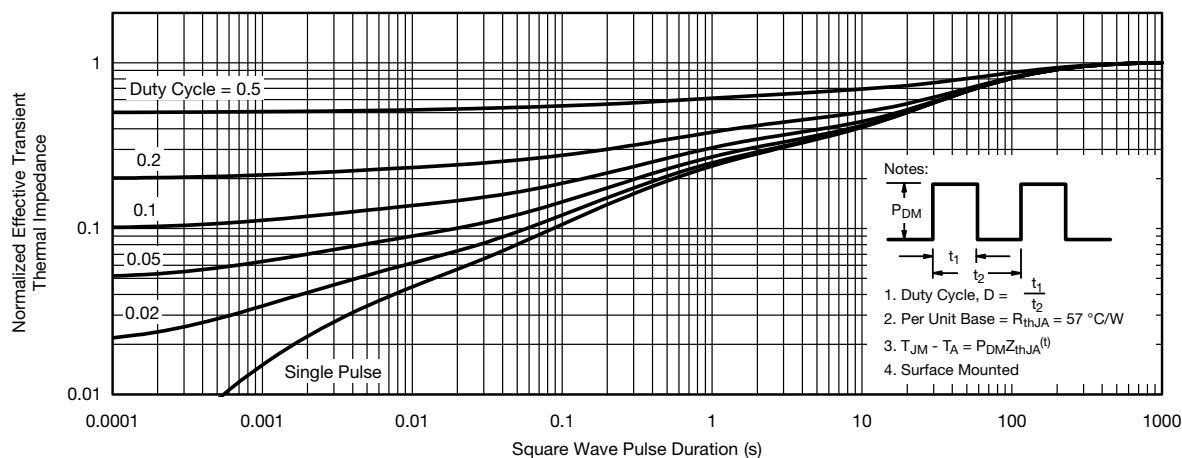
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage

Single Pulse Power

Safe Operating Area, Junction-to-Ambient

CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case
Note

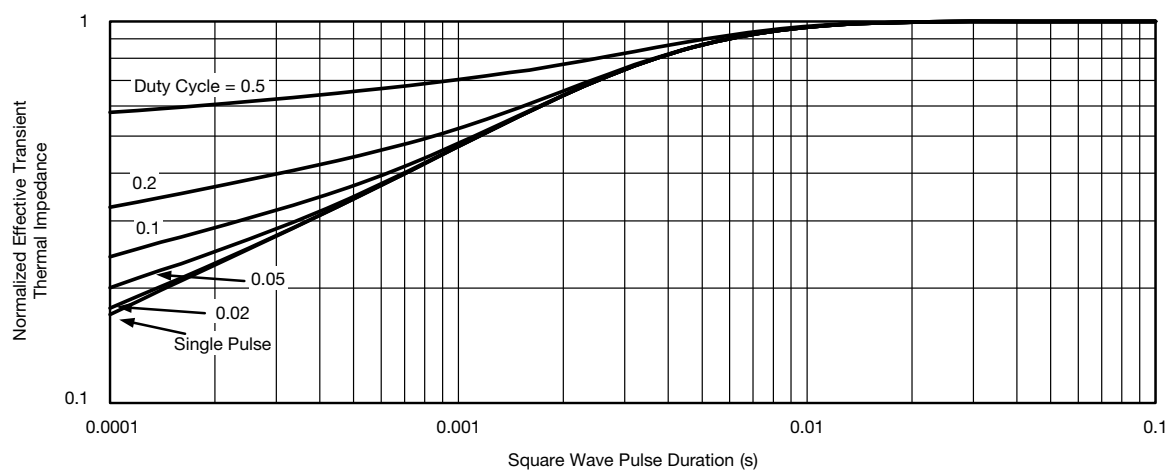
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



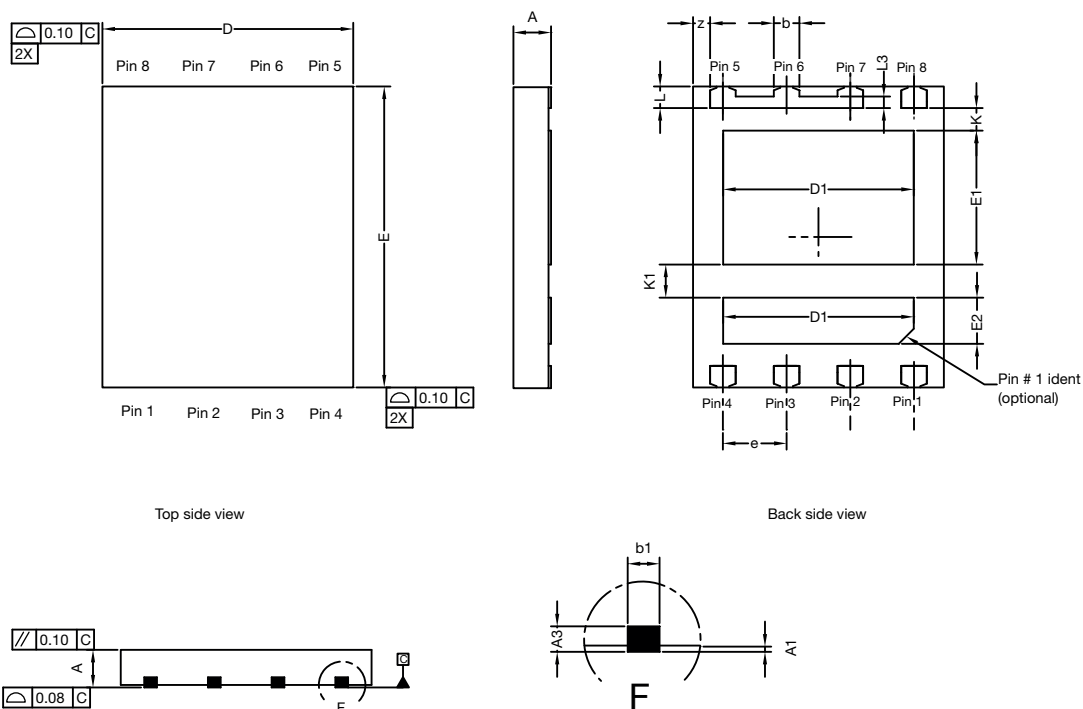
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

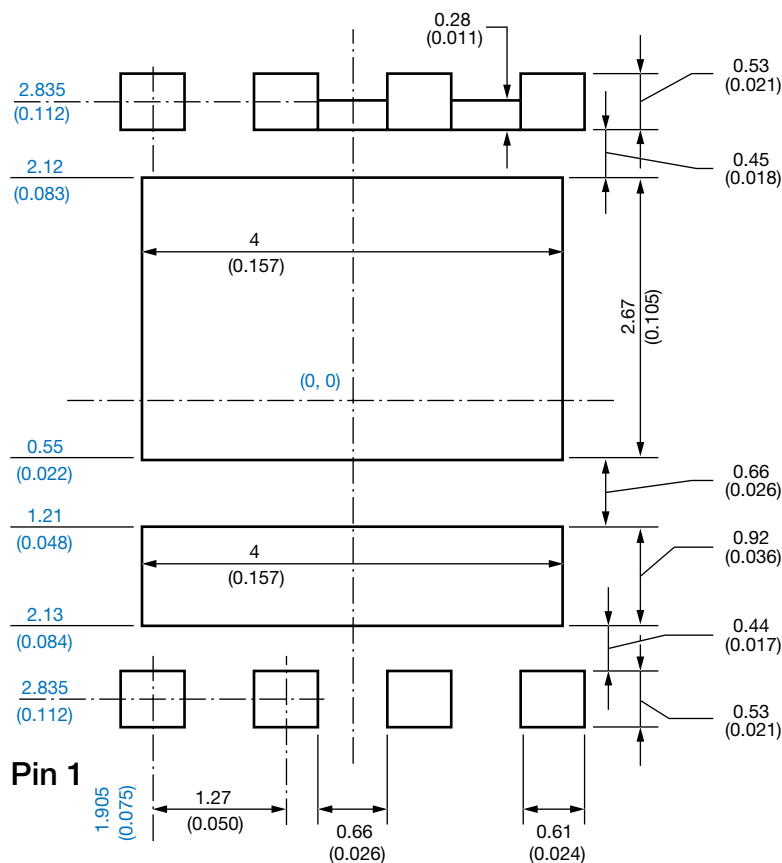
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PowerPAIR® 6 x 5 Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.028	0.030	0.032
A1	0.00	-	0.10	0.000	-	0.004
A3	0.15	0.20	0.25	0.006	0.007	0.009
b	0.43	0.51	0.61	0.017	0.020	0.024
b1	0.25 BSC			0.010 BSC		
D	4.90	5.00	5.10	0.192	0.196	0.200
D1	3.75	3.80	3.85	0.148	0.150	0.152
E	5.90	6.00	6.10	0.232	0.236	0.240
E1 Option AA (for W/B)	2.62	2.67	2.72	0.103	0.105	0.107
E1 Option AB (for BWL)	2.42	2.47	2.52	0.095	0.097	0.099
E2	0.87	0.92	0.97	0.034	0.036	0.038
e	1.27 BSC			0.050 BSC		
K Option AA (for W/B)	0.45 typ.			0.018 typ.		
K Option AB (for BWL)	0.65 typ.			0.025 typ.		
K1	0.66 typ.			0.025 typ.		
L	0.33	0.43	0.53	0.013	0.017	0.020
L3	0.23 BSC			0.009 BSC		
z	0.34 BSC			0.013 BSC		
ECN: T14-0782-Rev. C, 22-Dec-14						
DWG: 6005						

Recommended Minimum PAD for PowerPAIR® 6 x 5



Dimensions in millimeters (inch)

Note

- Linear dimensions are in black, the same information is provided in ordinate dimensions which are in blue.



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